



Material Content Data Sheet



Sales Product Name		BFP 843 H6327		Issued		20. July 2018			
MA#		MA001666944							
Package		PG-SOT343-4-2		Weight*		6.93 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.001	0.01		101		
	noble metal	gold	7440-57-5	0.003	0.04		394		
	inorganic material	silicon	7440-21-3	0.024	0.35	0.40	3465	3960	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100		
	non noble metal	titanium	7440-32-6	0.003	0.05		498		
	non noble metal	chromium	7440-47-3	0.010	0.15		1493		
	non noble metal	copper	7440-50-8	3.433	49.54	49.75	495588	497679	
wire	noble metal	gold	7440-57-5	0.009	0.13	0.13	1265	1265	
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4371		
	plastics	epoxy resin	-	0.651	9.40		93980		
	inorganic material	silicondioxide	60676-86-0	2.347	33.88	43.72	338766	437117	
leadfinish	non noble metal	tin	7440-31-5	0.199	2.88	2.88	28760	28760	
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31219	31219	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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